10

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a first lead having an inner portion on which a semiconductor chip is mounted, a second lead having an inner portion electrically connected to the semiconductor chip via a wire and a resin package for sealing the semiconductor chip and the wire. The inner portions, the semiconductor chip and the wire are coated with a coating film formed of amorphous fluororesin.

Englassials mailing outside EL 913562242US

Deter to Doposit THNUARY 11, 2002

Thoraby certain that the percentage in the second of the second